



67,200-327; TSMC 00-112  
Serial Number 09/885,784

RECEIVED  
2823

APP 18 2003

TECHNOLOGY CENTER 2800

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

**TO:** COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

**FROM:** Tung & Associates  
838 West Long Lake Road - Suite 120  
Bloomfield Hills, MI 48302

**DATE:** 8 April 2003

**REF:** APPLICANT : Liang //  
SERIAL NO. : 09/885,784 //  
ART UNIT : 2823 //  
FILING DATE : 20 June 2001  
ATT'Y NO. : 67,200-327; TSMC 00-132  
EXAMINER : Julio J. Maldonado  
TITLE : Laminating Method for Forming Integrated Circuit  
Microelectronic Fabrication

#12/E  
Ans +  
J.M. Maldonado  
4/22/03

Sir:

In response to an office action mailed on 25 March 2003, please consider the following amendments and remarks pertaining to the above referenced application.

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on April 10 2003.

  
Kathy Dixon